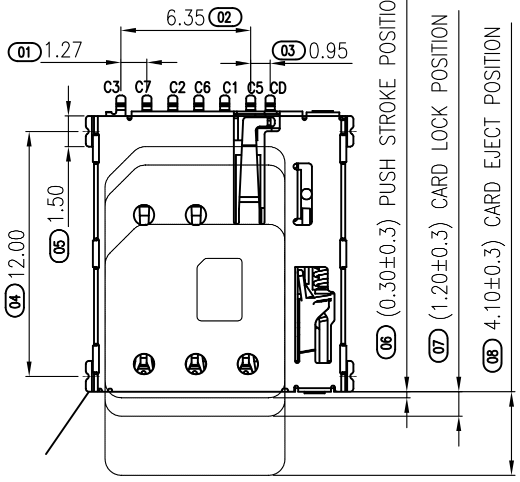
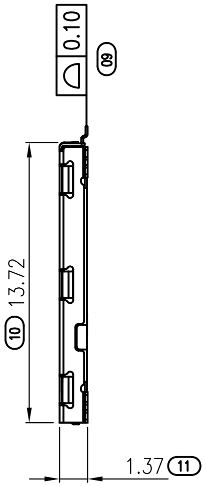
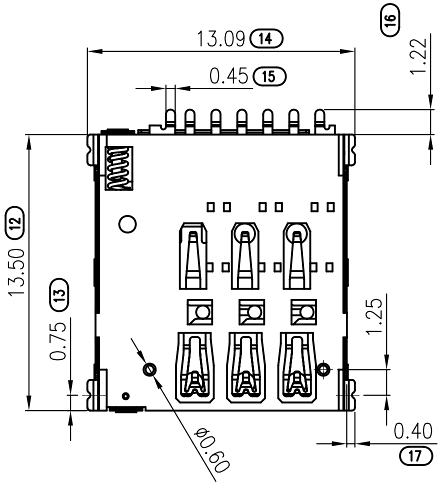
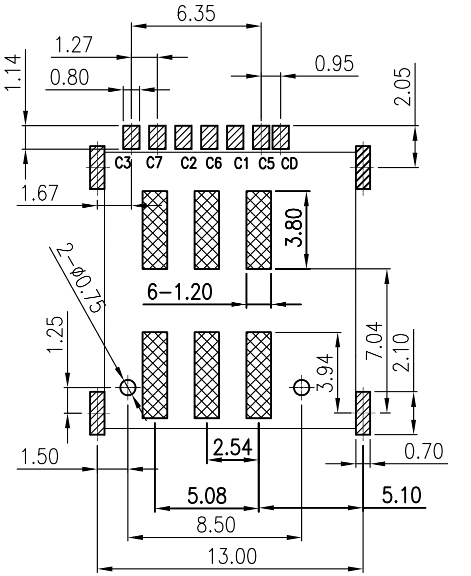
RoHS HSF



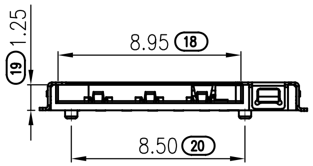


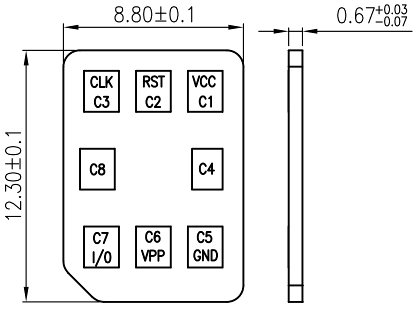




RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

▨ PAD
▩ KEEP OUT AREA





NANO SIM CARD

NOTES:

1)MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT:COPPER ALLOY
SHELL:STANLESS STEEL

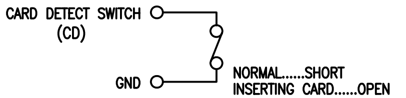
2). PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.

3. SPECIALITY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:50mΩ MAX
3.4 Insulation Resistance:1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:260+0/-5℃, 30±10s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition:Temperature-40℃~+85℃;
Humidity 80% R.H MAX

SIM pin Assignment

PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

CRICUIT DIAGRAM FOR CARD DETECT SWITCH



工程变更通知单号 ECN(DCN) NO.	版次 REV	日期 DATE	说明 DESCRIPTION	改变 CHANGE	承认 APPRO.
	A	19'/08/20	NEW RELEASE		

GENERAL TOLERANCE
UNLESS OTHERWISE NOTED

设计 DESIGN	Nicolas 19'/08/20
校阅 CHECK	Nicolas 19'/08/20
承认 APPRO.	

LXW 连兴旺电子(深圳)有限公司
LXWCONN ELECTRONICS(SHENZHEN)CO.,LTD

E	PROD	NANO SIM CARD
TITLE:	NANO SIM CARD H1.37 PUSH PUSH 有柱	
PART NO.	CS-314-07137PW	
SCALE	1:1	UNIT:mm 1 1